

Wafer Level Test Vertical Probe Design

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Abstract

The vertical probe of this paper used Si-wafer as substrate. The key point was to use buffer layers of low k elastomer to release uneven forces due to either non-uniform height of probe tips by the fabrication process, or uneven strains and stresses during the burn-in tests. In addition, the electrical cross-coupling effects among the probes can also be reduced by using low k elastomer. In addition, it can be applied for wafer level testing, and even high temperature burn-in. Because the CTE of which is equal to that of IC substrate.

Keyword : Wafer level test, Vertical probe, Low k elastomer